

V_{DSS}	600V
$R_{DS(on)(Max.)}$	0.104Ω
I_D	±42A
P_D	495W

●Features

- 1) Fast reverse recovery time (trr)
- 2) Low on-resistance
- 3) Fast switching speed
- 4) Drive circuits can be simple
- 5) Pb-free plating ; RoHS compliant

●Application

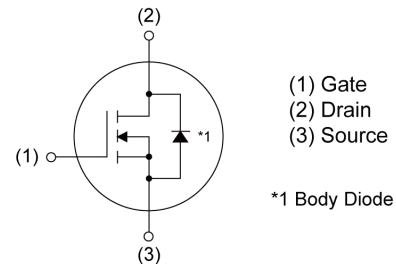
Switching applications

●Outline

TO-247G



●Inner circuit



●Packaging specifications

Packing	Tube
Packing code	C13
Marking	R6042JNZ4
Basic ordering unit (pcs)	600

●Absolute maximum ratings ($T_a = 25^\circ\text{C}$, unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain - Source voltage	V_{DSS}	600	V
Continuous drain current ($T_c = 25^\circ\text{C}$)	I_D^{*1}	±42	A
Pulsed drain current	I_{DP}^{*2}	±126	A
Gate - Source voltage	V_{GSS}	±30	V
Avalanche current, single pulse	I_{AS}^{*3}	8.9	A
Avalanche energy, single pulse	E_{AS}^{*3}	871	mJ
Power dissipation ($T_c = 25^\circ\text{C}$)	P_D	495	W
Junction temperature	T_j	150	°C
Operating junction and storage temperature range	T_{stg}	-55 to +150	°C

● Thermal resistance

Parameter	Symbol	Values			Unit
		Min.	Typ.	Max.	
Thermal resistance, junction - case	R_{thJC}	-	-	0.25	°C/W
Thermal resistance, junction - ambient	R_{thJA}	-	-	30	°C/W
Soldering temperature, wavesoldering for 10s	T_{sold}	-	-	265	°C

● Electrical characteristics ($T_a = 25^\circ\text{C}$)

Parameter	Symbol	Conditions	Values			Unit
			Min.	Typ.	Max.	
Drain - Source breakdown voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 1mA$	600	-	-	V
Zero gate voltage drain current	I_{DSS}	$V_{DS} = 600V, V_{GS} = 0V$ $T_j = 25^\circ\text{C}$	-	-	100	μA
Gate - Source leakage current	I_{GSS}	$V_{GS} = \pm 30V, V_{DS} = 0V$	-	-	± 100	nA
Gate threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 5.5mA$	5.0	6.0	7.0	V
Static drain - source on - state resistance	$R_{DS(on)}^{*5}$	$V_{GS} = 15V, I_D = 21A$ $T_j = 25^\circ\text{C}$	-	0.080	0.104	Ω
Gate resistance	R_G	$f = 1MHz, \text{open drain}$	-	1.2	-	Ω

● Electrical characteristics ($T_a = 25^\circ\text{C}$)

Parameter	Symbol	Conditions	Values			Unit
			Min.	Typ.	Max.	
Input capacitance	C_{iss}	$V_{GS} = 0V$	-	3500	-	pF
Output capacitance	C_{oss}	$V_{DS} = 100V$	-	200	-	
Reverse transfer capacitance	C_{rss}	$f = 1\text{MHz}$	-	2.5	-	
Effective output capacitance energy related	$C_{o(er)}^{*6}$	$V_{GS} = 0V$	-	145	-	
Effective output capacitance time related	$C_{o(tr)}^{*7}$	$V_{DS} = 0V \text{ to } 480V$	-	600	-	ns
Turn - on delay time	$t_{d(on)}^{*5}$	$V_{DD} \approx 300V, V_{GS} = 15V$	-	40	-	
Rise time	t_r^{*5}	$I_D = 21A$	-	30	-	
Turn - off delay time	$t_{d(off)}^{*5}$	$R_L \approx 14.3\Omega$	-	100	-	
Fall time	t_f^{*5}	$R_G = 10\Omega$	-	35	-	

● Gate charge characteristics ($T_a = 25^\circ\text{C}$)

Parameter	Symbol	Conditions	Values			Unit
			Min.	Typ.	Max.	
Total gate charge	Q_g^{*5}	$V_{DD} \approx 300V$	-	100	-	nC
Gate - Source charge	Q_{gs}^{*5}	$I_D = 42A$	-	30	-	
Gate - Drain charge	Q_{gd}^{*5}	$V_{GS} = 15V$	-	35	-	
Gate plateau voltage	$V_{(plateau)}$	$V_{DD} \approx 300V, I_D = 42A$	-	10.0	-	V

*1 Limited only by maximum temperature allowed.

*2 $P_w \leq 10\mu\text{s}$, Duty cycle $\leq 1\%$

*3 $L \approx 50\text{mH}$, $V_{DD} = 50V$, $R_G = 25\Omega$, starting $T_j = 25^\circ\text{C}$

*4 $T_c = 25^\circ\text{C}$

*5 Pulsed

*6 $C_{o(er)}$ is a fixed capacitance that gives the same stored energy as C_{oss} while V_{DS} is rising from 0 to 80% V_{DSS} .

*7 $C_{o(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 to 80% V_{DSS} .

●Body diode electrical characteristics (Source-Drain) ($T_a = 25^\circ\text{C}$)

Parameter	Symbol	Conditions	Values			Unit
			Min.	Typ.	Max.	
Source current	I_S^{*1}	$T_C = 25^\circ\text{C}$	-	-	42	A
Pulsed source current	I_{SP}^{*2}		-	-	126	A
Source-Drain voltage	V_{SD}^{*5}	$V_{GS} = 0\text{V}, I_S = 42\text{A}$	-	-	1.7	V
Reverse recovery time	t_{rr}^{*5}	$I_S = 42\text{A}$ $di/dt = 100\text{A}/\mu\text{s}$	-	110	-	ns
Reverse recovery charge	Q_{rr}^{*5}		-	460	-	nC
Peak reverse recovery current	I_{rr}^{*5}		-	8.5	-	A

● Electrical characteristic curves

Fig.1 Power Dissipation Derating Curve

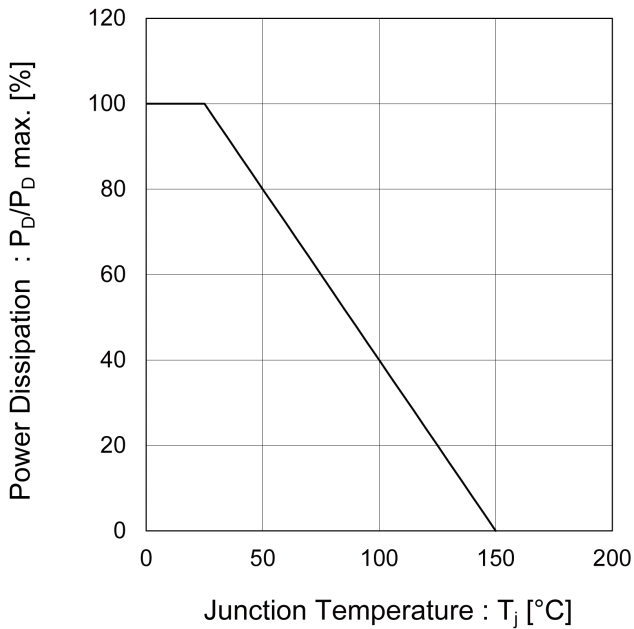


Fig.2 Drain Current Derating Curve vs. Junction Temperature

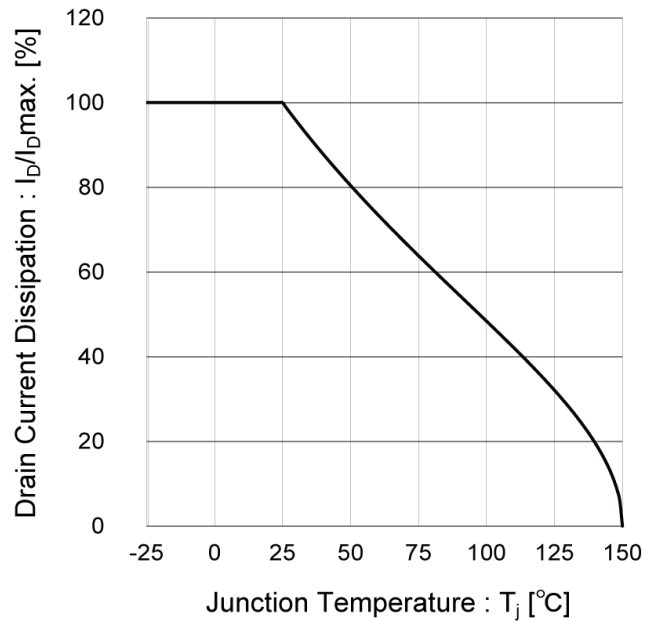


Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

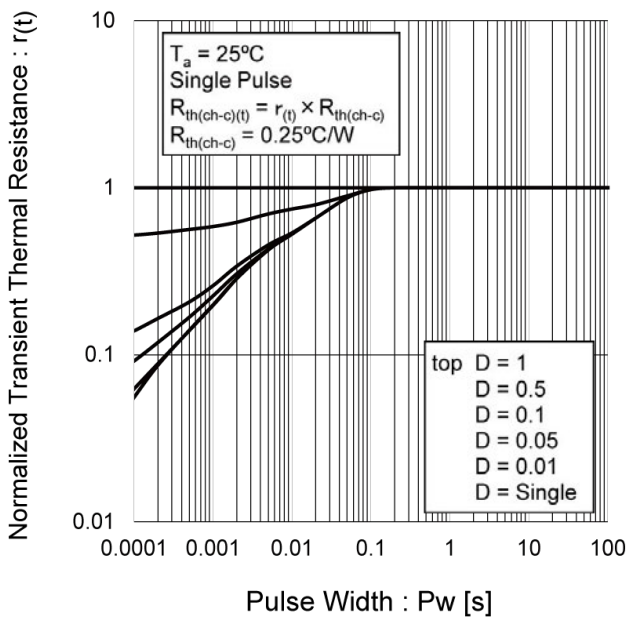
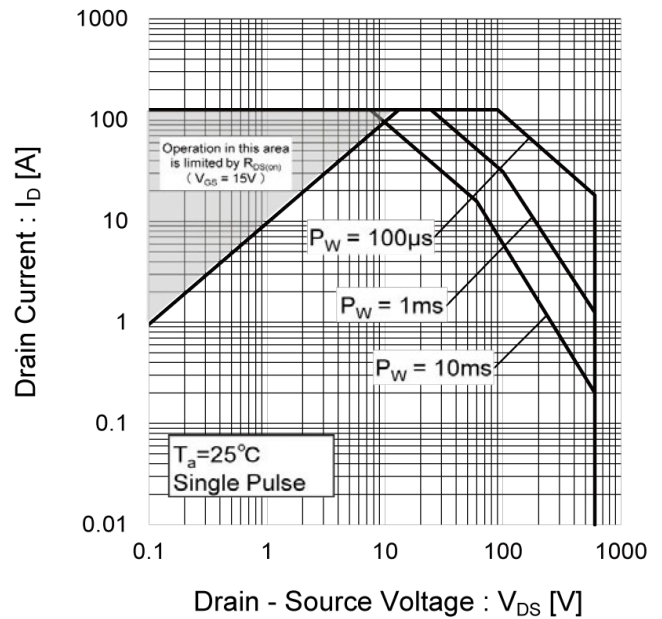


Fig.4 Maximum Safe Operating Area



● Electrical characteristic curves

Fig.5 Avalanche Energy Derating Curve vs. Junction Temperature

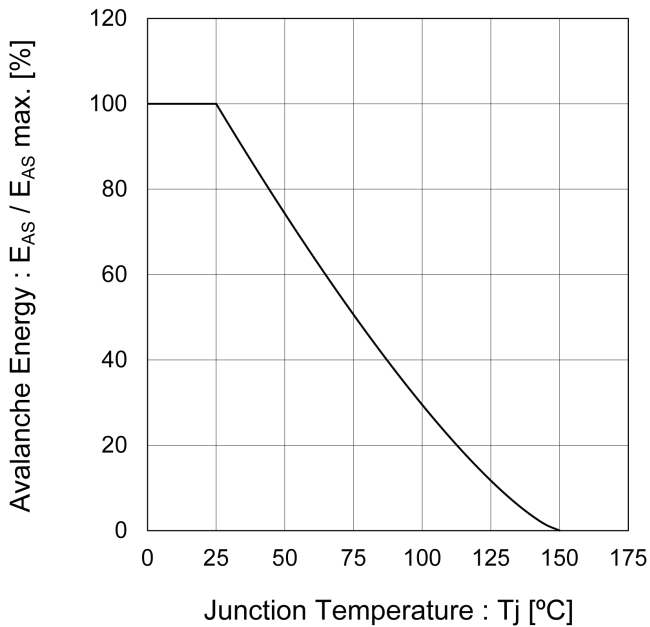


Fig.6 Normalized Breakdown Voltage vs. Junction Temperature

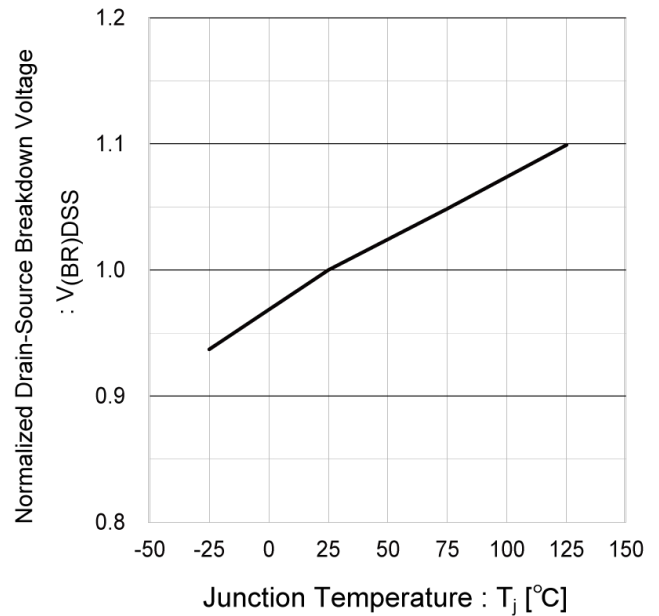


Fig.7 Typical Output Characteristics(I)

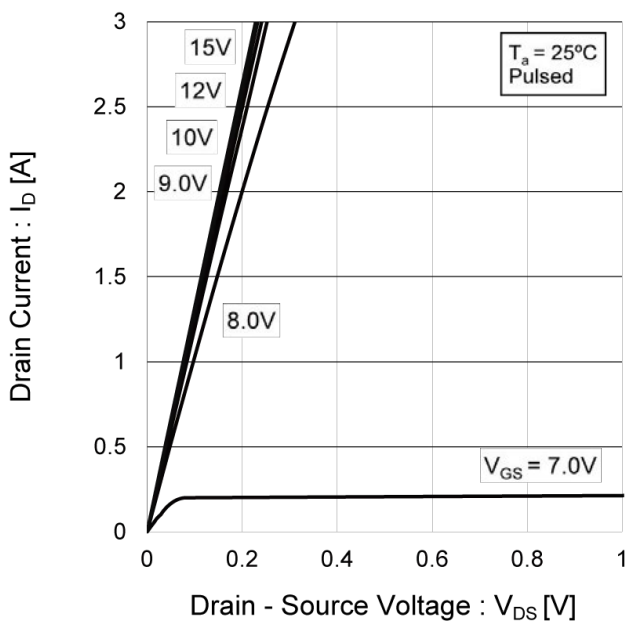
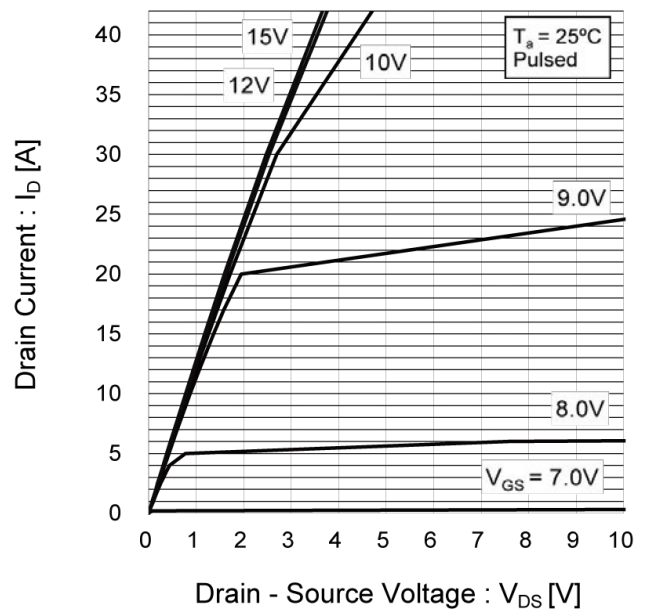


Fig.8 Typical Output Characteristics(II)



● Electrical characteristic curves

Fig.9 Typical Transfer Characteristics

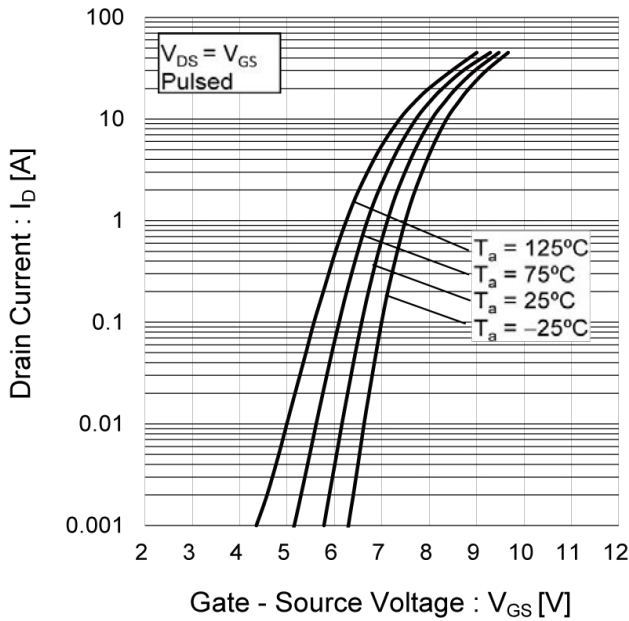


Fig.10 Normalized Gate Threshold Voltage vs. Junction Temperature

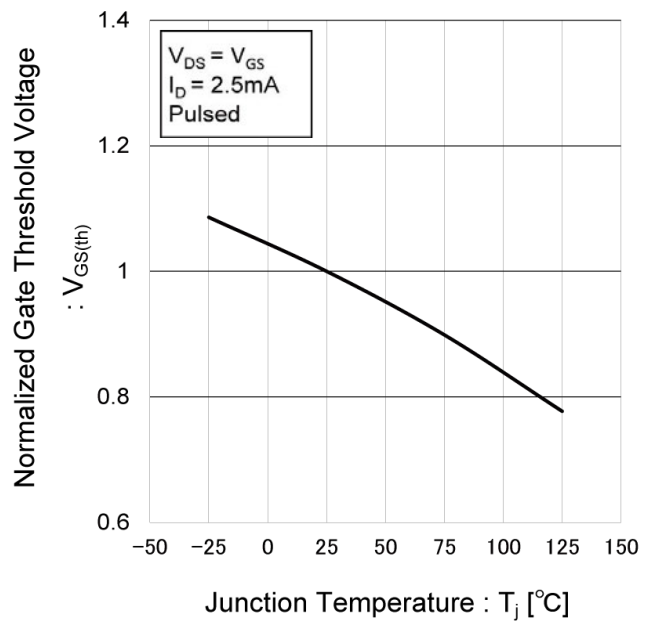


Fig.11 Static Drain - Source On - State Resistance vs. Gate Source Voltage

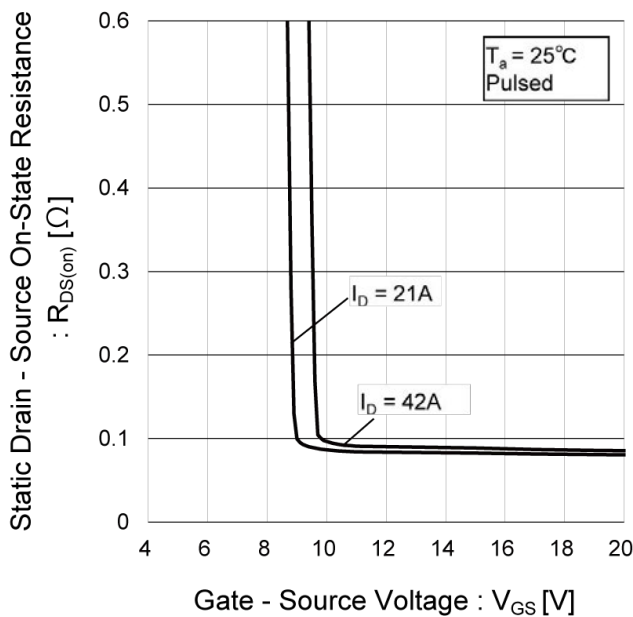
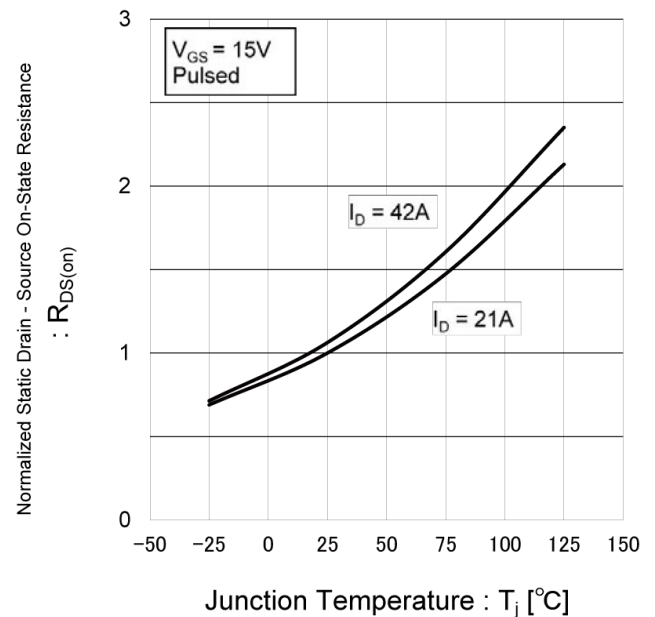


Fig.12 Normalized Static Drain - Source On - State Resistance vs. Junction Temperature



● Electrical characteristic curves

Fig.13 Static Drain - Source On - State Resistance vs. Drain Current(I)

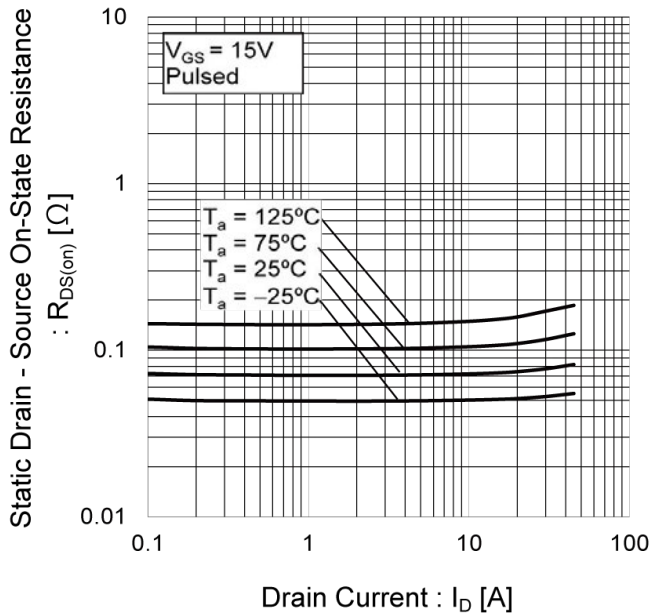


Fig.14 Typical Capacitance vs. Drain - Source Voltage

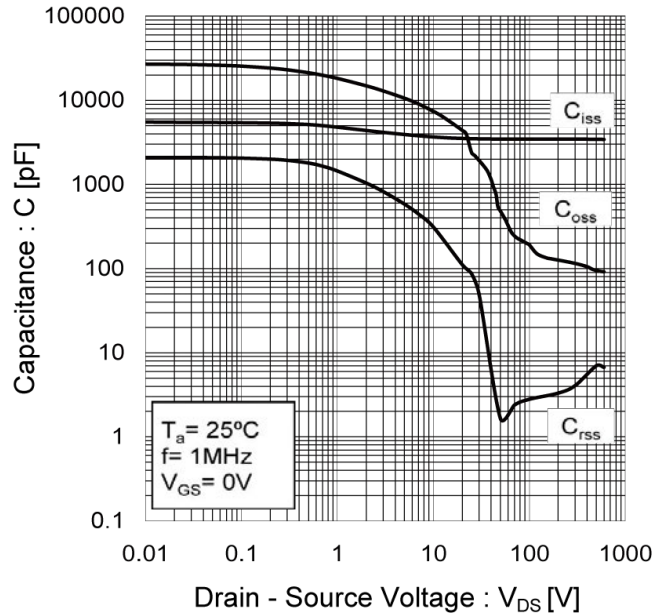


Fig.15 Typical Coss Stored Energy

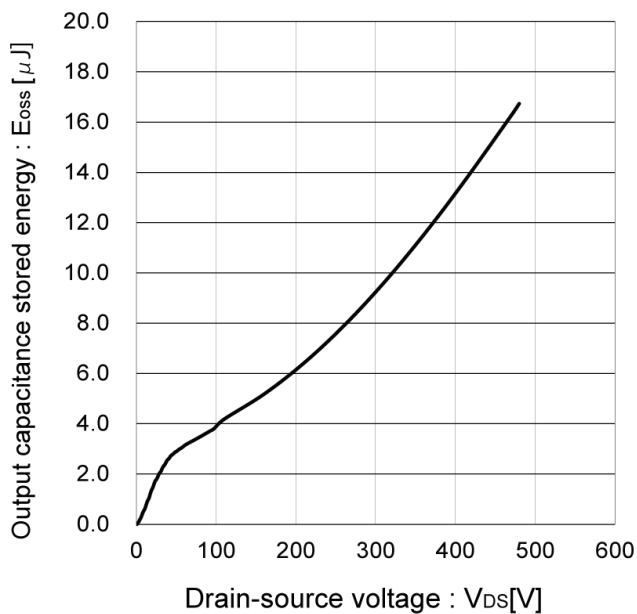
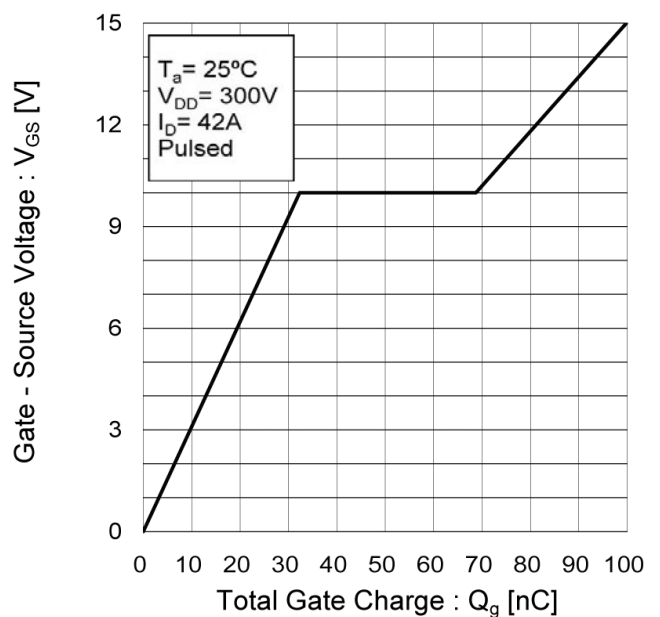


Fig.16 Dynamic Input Characteristics



● Electrical characteristic curves

Fig.17 Inverse Diode Forward Current vs. Source - Drain Voltage

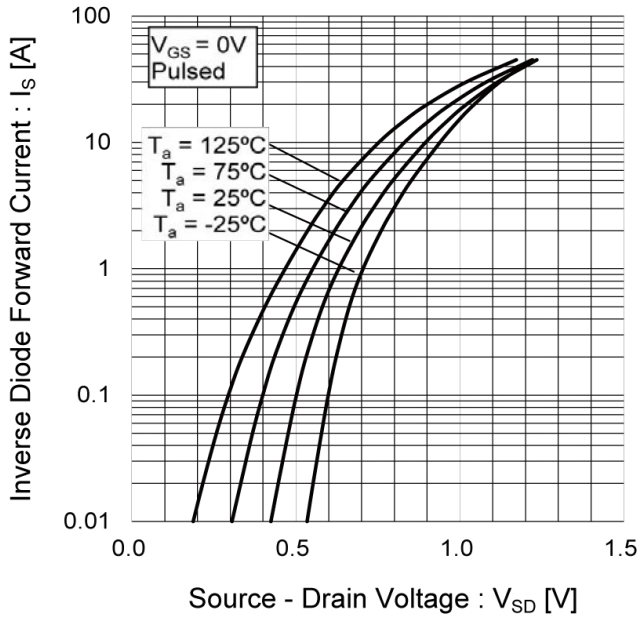
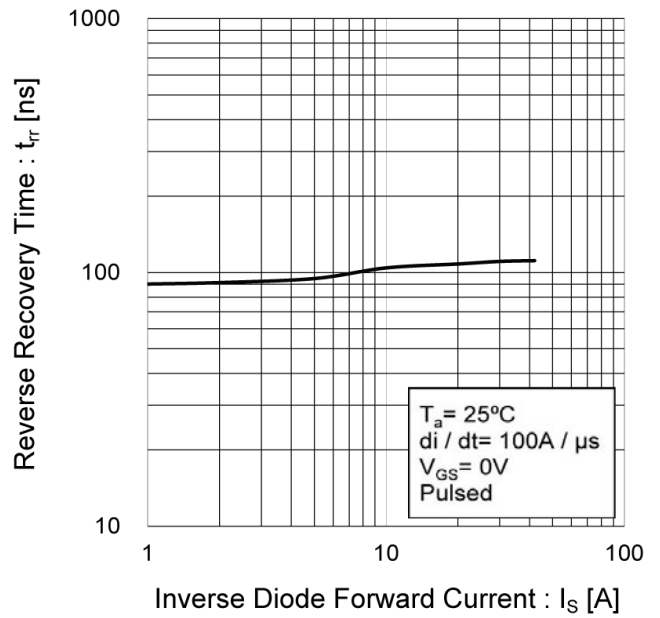


Fig.18 Reverse Recovery Time vs. Inverse Diode Forward Current



● Measurement circuits

Fig.1-1 Switching Time Measurement Circuit



Fig.1-2 Switching Waveforms

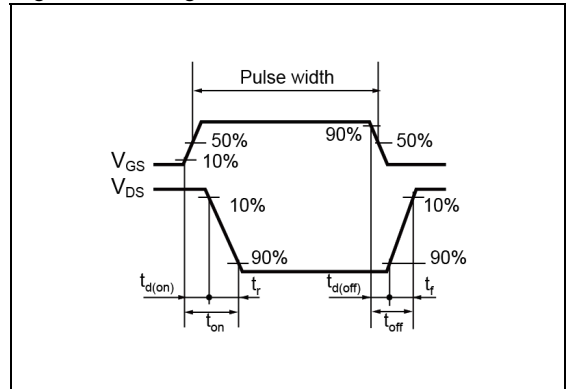


Fig.2-1 Gate Charge Measurement Circuit



Fig.2-2 Gate Charge Waveform

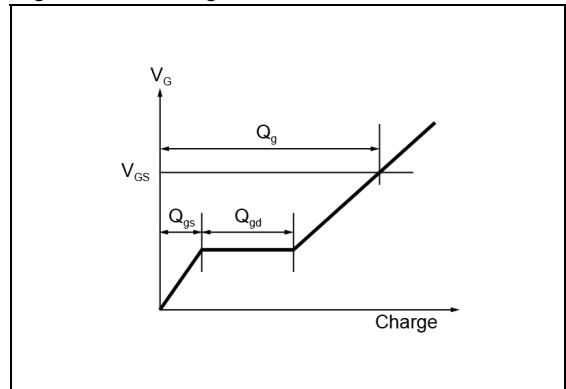


Fig.3-1 Avalanche Measurement Circuit



Fig.3-2 Avalanche Waveform

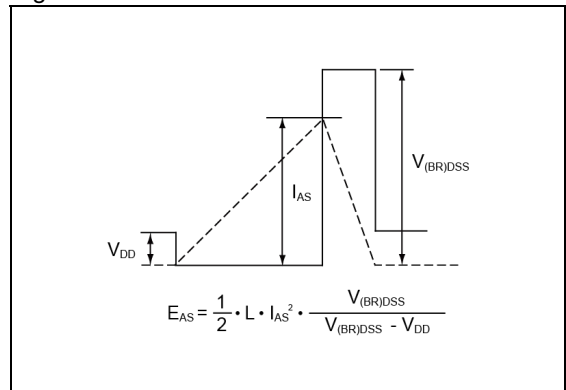


Fig.4-1 Diode Characteristic Measurement Circuit

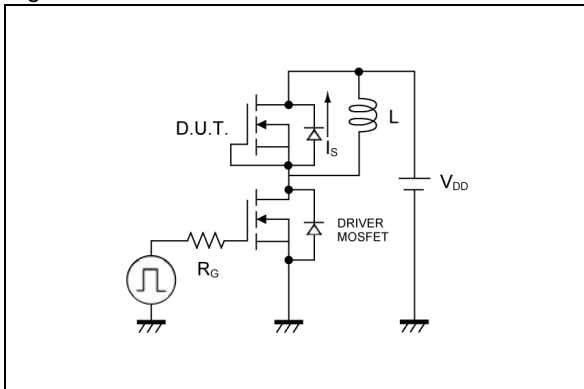
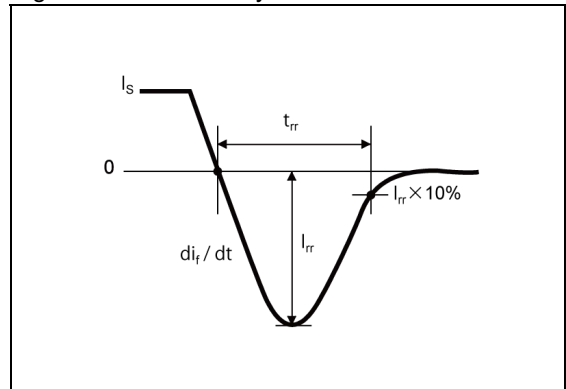


Fig.4-2 Diode Recovery Waveform



●Dimensions

TO-247



DIM	MILIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.82	5.22	0.190	0.206
A1	2.11	2.71	0.083	0.107
A2	1.80	2.20	0.071	0.087
b	1.00	1.40	0.039	0.055
b1	1.80	2.20	0.071	0.087
b2	2.80	3.20	0.110	0.126
c	0.45	0.75	0.018	0.030
D	20.65	21.25	0.813	0.837
E	15.64	16.24	0.616	0.639
e	5.44		0.214	
L	19.77	20.37	0.778	0.802
L1	4.09	4.29	0.161	0.169
P	3.51	3.71	0.138	0.146
S	5.97	6.37	0.235	0.251

Dimension in mm/inches

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CLASS IV		CLASS III	

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- In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- Confirm that operation temperature is within the specified range described in the product specification.
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- When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
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 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
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